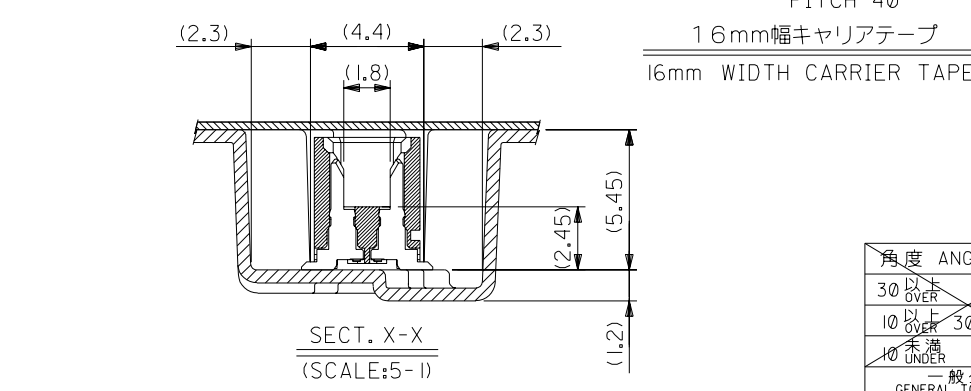
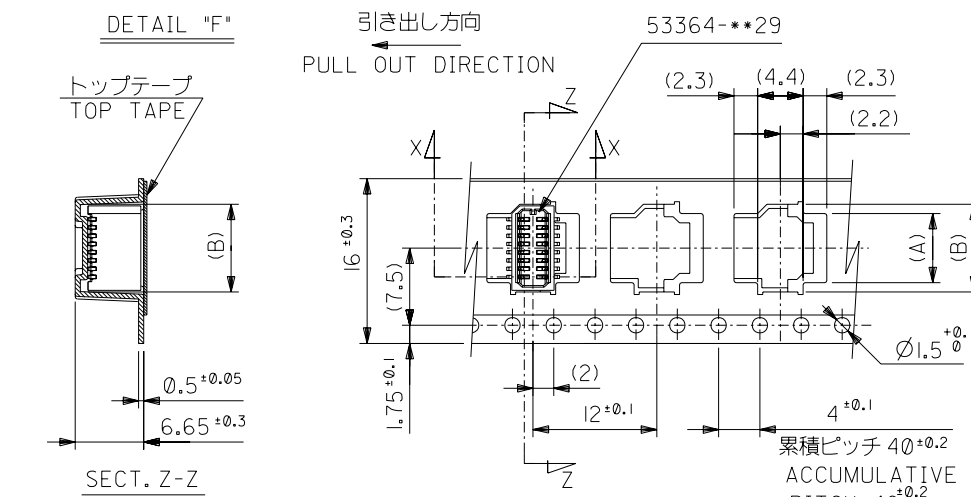
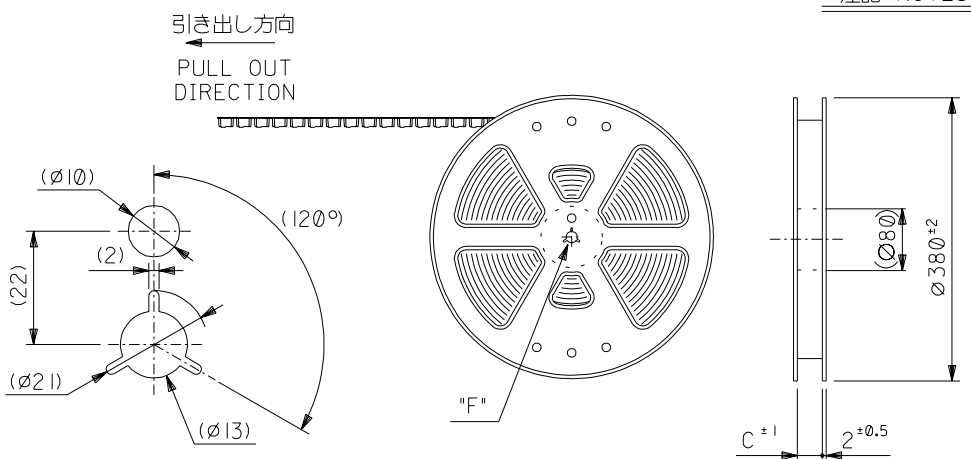
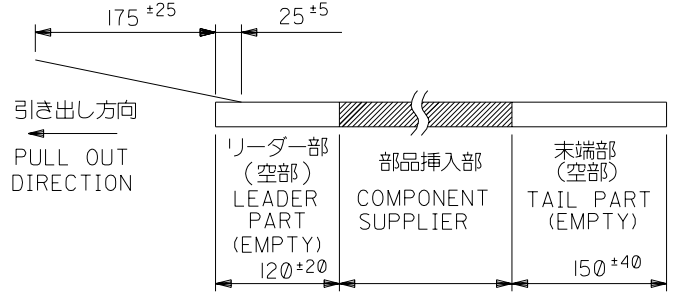


DWG. NO. SD-53364-**-71

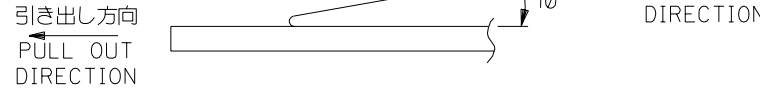


注記 NOTES

1. 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



3. トップテープの剥離強度：(剥離方向は下図参照)
0.1N ~ 1.3N(10gf ~ 130gf) 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)
- PEELING OFF FORCE OF TOP TAPE
0.1N ~ 1.3N(10gf ~ 130gf) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION

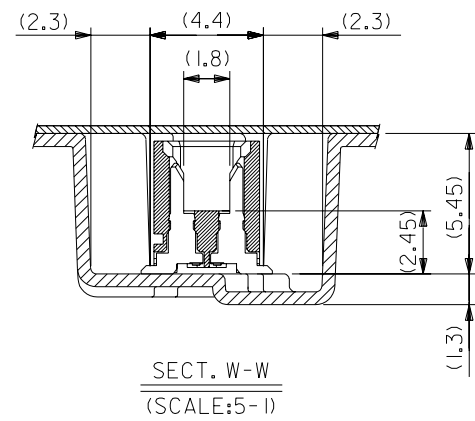
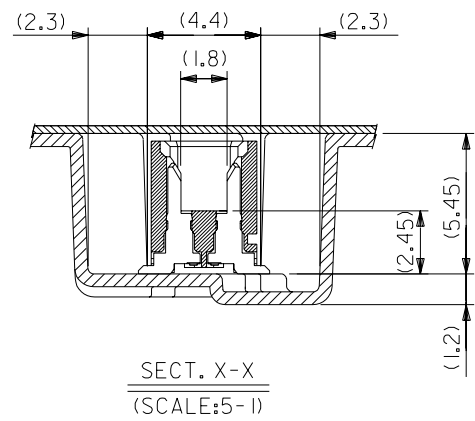
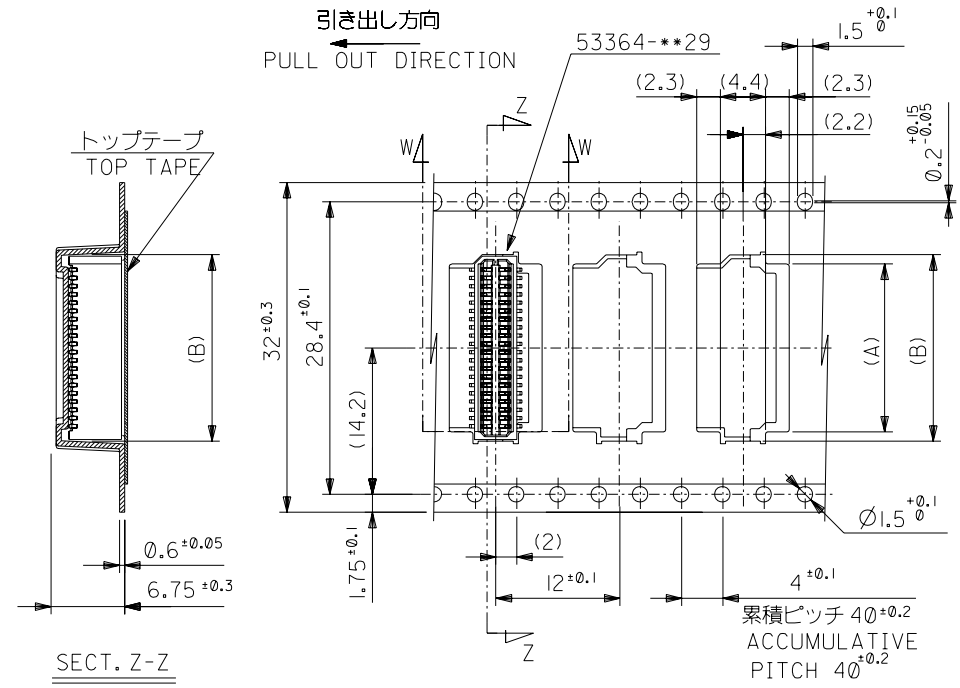
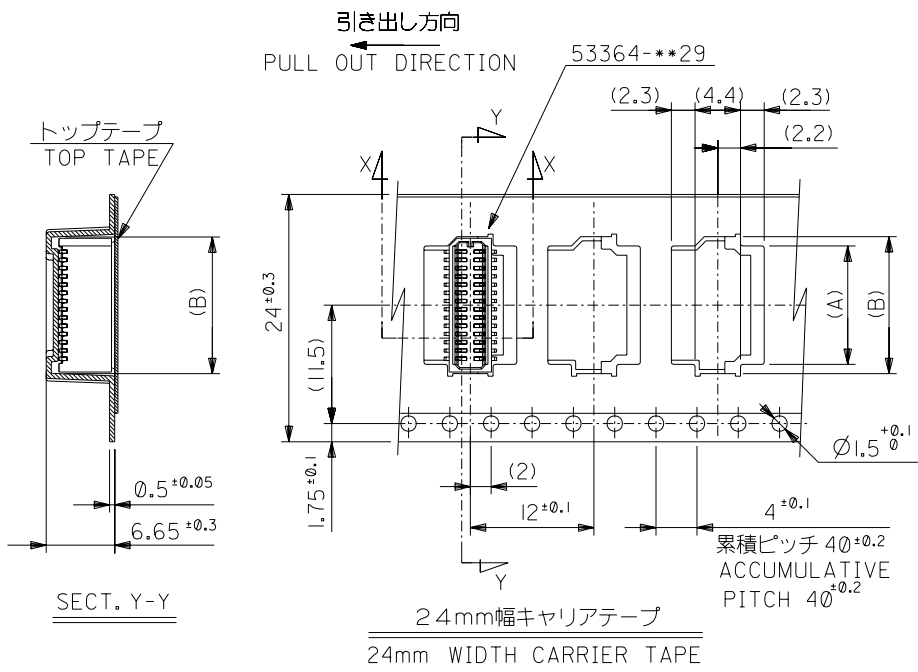


4. 材料 MATERIAL
キャリアテープ：ポリプロピレン (PP) CARRIER TAPE:POLYPROPYLENE
トップテープ：PET, PE, PEF TOP TAPE:PET,PE,PEF
リール：ポリスチレン (PS) REEL:POLYSTYREN(PS)
<リサイクル材を含む> <RECYCLE MATERIAL CONTAINED>
5. 本製品は 53364-**-91 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53364-**-91.

16	17.5	9.3	7.5	53364-1871	18
		6.9	5.1	53364-1271	12
		6.1	4.3	53364-1071	10
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	MATERIAL. NO.	極数 CIRCUIT

材料 MATERIAL 注記参照 SEE NOTES		MATERIAL 注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH —#—		REVISION RECORD		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE —#—		DRAWN BY '03/12/11 M.NINOMIYA		TITLE 名称	
被覆外径 INS. RANGE —#—		CHK'D BY '03/12/11 K.TOJO		0.8 BtB Conn Wafer Assy ST SMT Without Boss Embstp Pkg -LEAD FREE-	
DRAWN BY '03/12/11 M.NINOMIYA		CHK'D BY '03/12/11 K.TOJO		DWG. NO. (SHEET 1 OF 2)	
APP'D BY '03/12/11 M.SASAO		SCALE —#—		SD-53364-**-71	
REV 0					

角度 ANGLE	±3°
30以上 OVER	±0.3
10以上 未満 OVER 30 UNDER	±0.25
未満 10 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

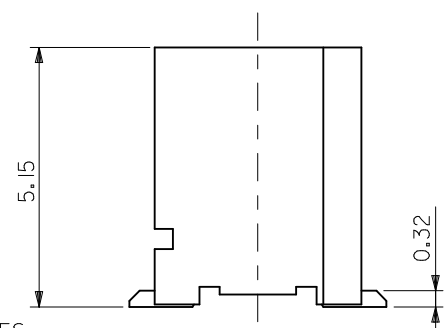
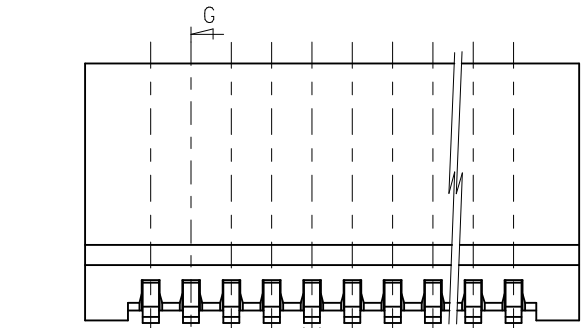
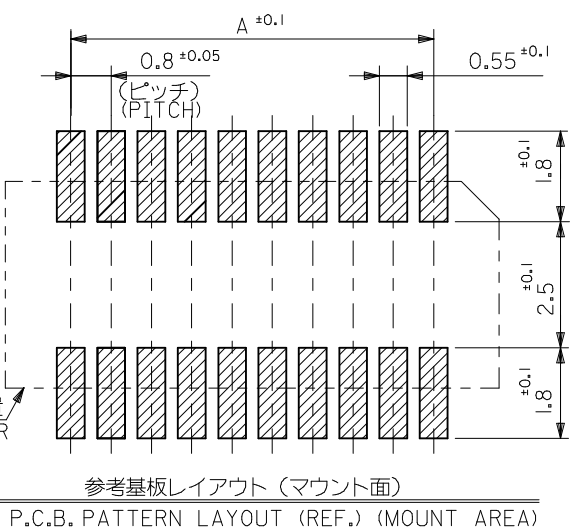
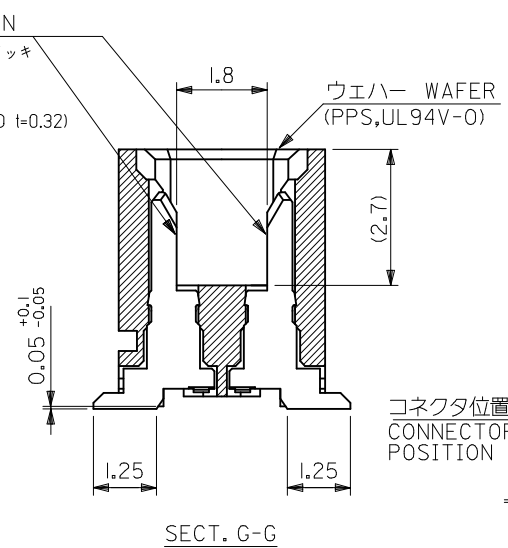
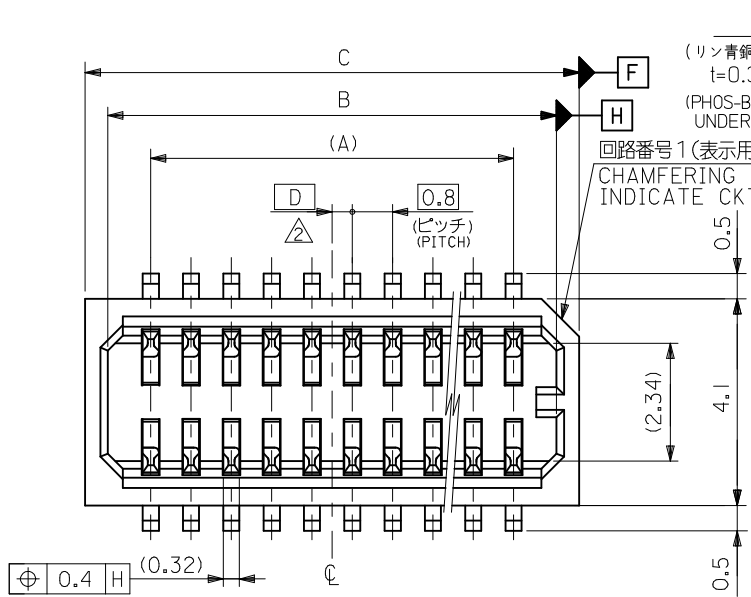


32	33.5	18.9	17.1	53364-4271	42
		18.1	16.3	53364-4071	40
24	25.5	16.5	14.7	53364-3671	36
		14.1	12.3	53364-3071	30
		13.3	11.5	53364-2871	28
		10.1	8.3	53364-2071	20
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

材料 MATERIAL	SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
仕上げ FINISH	—#—		REVISE ONLY ON CAD SYSTEM	
適用電線範囲 WIRE RANGE	—#—		TITLE 名称	
被覆外径 INS. RANGE	—#—		0.8 BtB Conn Wafer Assy ST SMT Without Boss Embstp Pkg -LEAD FREE-	
DRAWN BY '03/12/11 M.NINOMIYA	CHK'D BY '03/12/11 K.TOJO	DR. '03/12/11 M.SASAO	尺度 SCALE	—#—
記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE	
① 新規作成 (J2004-1478) RELEASED	MN KT			
一般公差 GENERAL TOLERANCES	DWG. NO. (SHEET 2 OF 2) REV SD-53364-**-71 ①			

角度 ANGLE	±30°
30 以上 OVER	±0.3
10 以上 30 未満 OVER 30 UNDER	±0.25
未満 10 UNDER	±0.2

10 9 8 7 6 5 4 3 2 1

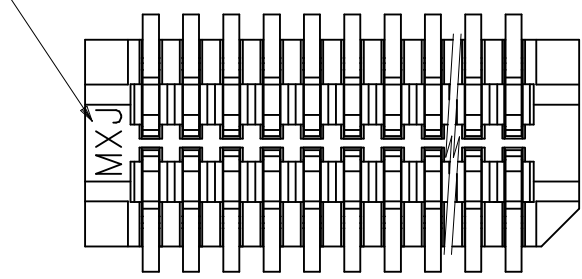


注記 NOTES

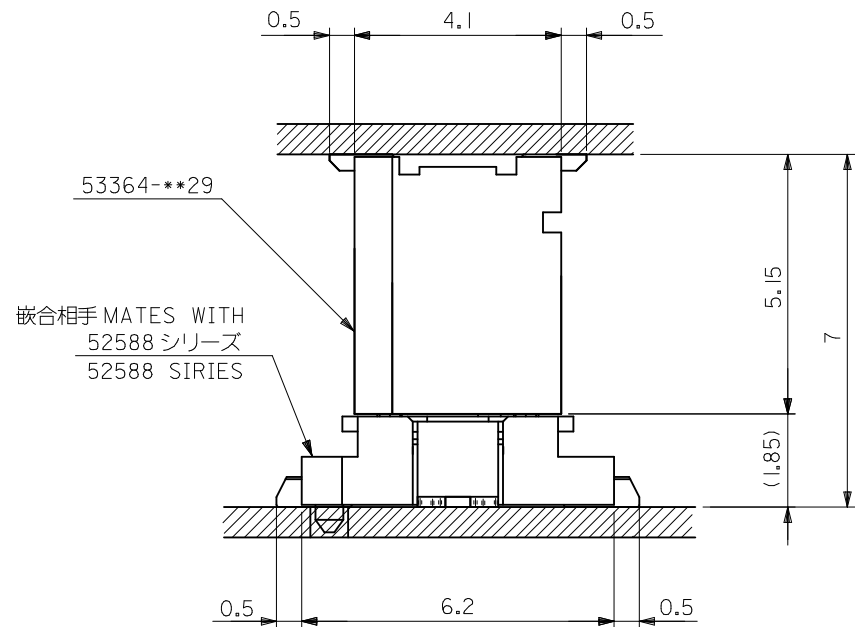
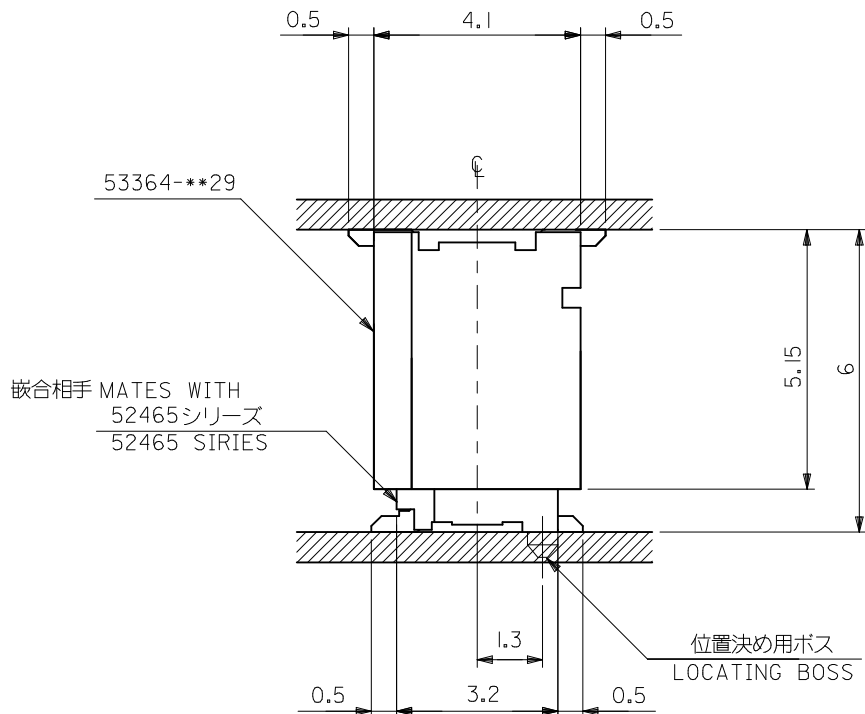
1. 嵌合相手 : 52465, 52588 シリーズ
MATES WITH : 52465, 52588 SERIES
2. ウェハーの ϕ から隣接するピンの ϕ 迄の位置を示す。
SHOW POSITION FROM ϕ OF WAFER TO ϕ OF ADJACENT PINS.
3. 本製品は 53364-**-27 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53364-**-27.

0.4	17.8	16.9	15.2	53364-4029	40
0.4	16.2	15.3	13.6	53364-3629	36
0.8	13.8	12.9	11.2	53364-3029	30
0.4	13.0	12.1	10.4	53364-2829	28
0.4	9.8	8.9	7.2	53364-2029	20
0.8	9.0	8.1	6.4	53364-1829	18
0.4	6.6	5.7	4.0	53364-1229	12
0.8	5.8	4.9	3.2	53364-1029	10
D	C	B	A	MATERIAL. NO.	極数 CKT.

トレードマーク TRADE MARK



REVISED EC NO. J2009-1121 DRWN: MAKURAA 2008/12/15 CHKD: T. HARUYAMA 2008/12/15 APPR: NUKITA 2009/01/13	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M. NINOMIYA		DATE '03/12/11		TITLE 0.8 BOARD TO BOARD CONN. WAFER ASSY ST. SMT -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO		DATE '03/12/11		MOLEX INCORPORATED DOCUMENT NO. SD-53364-003 SHEET NO. 1 OF 2				
		30 OVER	±0.3	APPROVED BY M. SASAO		DATE '03/12/11						
REV	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



嵌合状態図 (参考)
MATED DRAWING (REF.)

REVISED EC NO: J2009-1121 DRWN: KAKIMURA 2008/12/15 CHKD: T. HARUYAMA 2008/12/15 APPR: NUKITA 2009/01/13	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY M. NINOMIYA	DATE '03/12/11	TITLE 0.8 BOARD TO BOARD CONN. WAFER ASSY ST. SMT -LEAD FREE-	
	10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '03/12/11		
	30 OVER	± ---	APPROVED BY M. SASAO	DATE '03/12/11	MOLEX INCORPORATED	
	ANGULAR	± --- °	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-53364-003		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			